

# PATENT ABSTRACTS OF JAPAN

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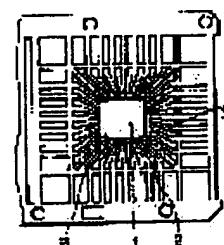
## (54) LEAD FRAME

### (57) Abstract:

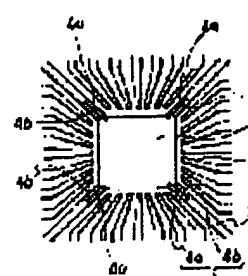
PURPOSE: To prevent deformation or open circuit of a wire, package crack, and the like due to variation in the position or direction, especially floating, of a die pad or a semiconductor element supported thereon caused by the pressure of resin at the time of resin sealing by enhancing the mechanical strength at the depress part of a support lead.

CONSTITUTION: In a lead frame where the root part of a lead 2 supporting a die pad 1 which supports a semiconductor element is depressed, the depressed part 4 of the support lead 2 is split into a plurality of subsections 4a, 4b. One subsection 4a is set longer than the other subsection 4b wherein the subsections 4a, 4b and the support lead 2 of the die pad 1 substantially define a triangle, when the depressed part is viewed from the side, thus providing a reinforcing part.

(A)



(B)



(C)



## LEGAL STATUS

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